Overview

The following document describes a 12 V / 20 A output switch mode power supply (SMPS) intended for use as an ATX power supply main converter or as an All−In−One PC power supply. The reference design circuit consists of a double sided 135 x 200 mm printed circuit board with a height of only 35 mm. An overview of the entire SMPS architecture is provided in Figure 1. Careful consideration was given to optimizing performance while minimizing the total solution cost.

**Figure 1. Demoboard Block Diagram**

**Architecture Overview**

The circuit utilizes the NCP1605 for an active power factor correction front end. This stage provides a well regulated PFC output voltage that allows optimization of the downstream converter. The NCP1605 controller operates using a Frequency Clamped Critical conduction Mode control technique. The SMPS stage uses a Half Bridge Resonant LLC topology since it improves efficiency, reduces EMI signature and provides better transformer utilization compared to conventional topologies. The NCP1397B controller is used to control the Half Bridge Resonant LLC converter. To maximize efficiency of the LLC power stage, Synchronous Rectification (SR) has been implemented on the secondary side. The NCP4303B SR controller is used to achieve accurate turn−on and turn−off of the SR MOSFETs.

In summary, the architecture selected for this reference design allows system optimization so that the maximum efficiency is achieved without significantly increasing the component cost and circuit complexity.

**Demoboard Specification**

Most of today’s computing applications like ATX PC, game consoles and All−in−one PC use 12 V as the main power rail. This voltage is then further decreased to 5 V and 3.3 V by DC/DC step down converters. Because nearly all power passes through the 12 V output, it is critical that the efficiency of the main power stage be optimized. Most designs today utilize an LLC topology for the power stage to provide high efficiency at a reasonable cost. The LLC power stage provides inherently high efficiency results thanks to zero voltage switching (ZVS) on the primary side and zero current switching (ZCS) on the secondary side. Efficiency however decreases for higher output currents as the secondary RMS current reaches a high level. The solution for these losses on the secondary side is to use synchronous rectification instead of conventional rectifiers (Schottky diode). Consideration was also given to optimizing light and no load efficiency, which is particularly important in All−in−one PC SMPS that usually do not utilize an additional standby power supply.
Based on the above considerations, the following is the required specifications of the SMPS reference design:

### Table 1. DEMOBOARD SPECIFICATION

<table>
<thead>
<tr>
<th>Requirement</th>
<th>Min</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>Input voltage (ac)</td>
<td>90</td>
<td>265</td>
<td>V</td>
</tr>
<tr>
<td>Output voltage (dc)</td>
<td>−</td>
<td>12</td>
<td>V</td>
</tr>
<tr>
<td>Output current</td>
<td>0</td>
<td>20</td>
<td>A</td>
</tr>
<tr>
<td>Total output power</td>
<td>0</td>
<td>240</td>
<td>W</td>
</tr>
<tr>
<td>Consumption for a 500 mW output load in STBY mode</td>
<td>−</td>
<td>1.7</td>
<td>W</td>
</tr>
<tr>
<td>Consumption for a 100 mW output load in STBY mode</td>
<td>−</td>
<td>1.2</td>
<td>W</td>
</tr>
<tr>
<td>No load consumption SR operating</td>
<td>−</td>
<td>870</td>
<td>mW</td>
</tr>
<tr>
<td>No load consumption SR turned off, no bypass Shottky used</td>
<td>−</td>
<td>1</td>
<td>W</td>
</tr>
<tr>
<td>Load regulation</td>
<td></td>
<td>20</td>
<td>mV</td>
</tr>
</tbody>
</table>

The NCP4303A/B provides the following beneficial features for SR implementation in an LLC power stage:

**Precise Zero Current Detection with Adjustable Threshold**

The NCP4303 SR controller provides a default Zero Current Detection (ZCD) threshold of 0 mV. A 100 μA current source on the CS input allows the customer to decrease this basic ZCD threshold by using a resistor in series with the CS input. The turn–off current threshold can therefore be precisely adjusted down to 0 A to maximize the SR MOSFET conduction time. The result is optimized system efficiency.

**Typically 40 ns Turn–off Delay from Current Sense Input to Driver Output**

Once the CS input detects that the secondary current has reached zero, it is necessary to turn–off the SR MOSFET as fast as possible. The extremely low 40 ns propagation delay of the NCP4303 assures that the SR MOSFET will be turned–off quickly, avoiding reverse current flow back into the transformer winding from the secondary filtering capacitor.

**Automatic Parasitic Inductance Compensation Input**

The high secondary RMS current in the LLC stage has a high $\text{di/dt}$ product that can induce a high error voltage on the parasitic inductances of the SR MOSFET package (TO220 for instance). Parasitic error voltages shift the drain to source voltage and affect the accuracy of the ZCD system. As a result, the SR MOSFET is turned–off prematurely and efficiency is decreased. NCP4303 offers a method to compensate for this effect via a special input that offsets the ZCD comparator threshold with a compensation voltage. Thanks to this feature, the ZCD comparator can perform precise detection independent of the secondary current $\text{di/dt}$ product. This technique allows the use of standard leaded SR MOSFETs, which can reduce assembly process costs (SMT MOSFETs usually require a more expensive PCB and soldering).

**Current Sense Pin Capability of 200 V**

The high voltage capability of the CS pin allows for direct connection to the SR MOSFET drain. This avoids the use of a high impedance series resistor which would delay the CS signal.

**Disable Input to Enter Standby or Low Consumption Mode**

The trigger/disable input integrates two functions: 1st it can be used to turn–off the SR MOSFET in Continuous Current Mode applications (like CCM flyback). 2nd it can be used to switch the controller into standby mode. The SR standby mode decreases SMPS power consumption when the output is not loaded. Parallel Schottky diodes can be used for conduction in this mode rather than the SR MOSFETs.

**Adjustable Minimum On and Off Times Independent of VCC Level**

Due to the various impedances in the application (parasitic inductances and capacitances) spurious ringing can occur after the SR MOSFET is turned on or off. To overcome controller false switching due to this parasitic ringing, the NCP4303 utilizes adjustable minimum on and off times. The driver state cannot be changed during these minimum periods. The duration of the minimum on time and minimum off time can be adjusted independently of each other and independent of the IC Vcc level.

**5 A / 2.5 A Peak Current Sink / Source Drive Capability**

The SR MOSFETs for high current applications usually feature high input capacitance. The strong sink driver capability of the NCP4303 decreases the turn–off time and thus allows for optimized conduction time of the SR MOSFET.

**Operating Voltage Range Up to 30 V**

The NCP4303 VCC input can be connected directly to the application output voltage without any additional pre–regulation. This feature simplifies driver implementation and reduces application cost.

**Gate Driver Clamp of Either 12 V (NCP4303A) or 6 V (NCP4303B)**

Some of today’s SR MOSFETs provide low channel resistance for lower gate voltages (< 6 V). Thus it is beneficial to clamp the driver voltage at a lower level and reduce driving losses. This technique helps to maintain high efficiency, especially under medium and light load conditions. On the other hand, some MOSFETs still require higher gate voltage. NCP4303A provides 12 V gate driver clamp for these cases. Please refer to the datasheet for more...
information and a detailed description of the NCP4303A/B SR controller.

**Detailed Demoboard Description**

A complete schematic of the demoboard is shown in Figure 58. As mentioned above, the SMPS is composed of three blocks. The PFC front stage accepts input voltages from 90 V ac / 60 Hz up to 265 V ac / 50 Hz and converts it to 395 Vdc nominal. The second block is the LLC power stage that converts the bulk voltage to 12 V / 20 A output. The third block is the synchronous rectification which replaces conventional Schottky rectifiers.

**PFC Front Stage**

The input voltage passes through an EMI filter (Figure 2), which protects the distribution network against noise generated by the SMPS. The EMI filter is composed of capacitors CY1, CY2, C33, C47, current compensated choke L15 and differential mode chokes L12, L13. Varistor R48 protects the SMPS from surges passed from the mains.

Filtered ac voltage is rectified by a bridge rectifier B1 and connected to the PFC power stage.

To minimize the risk of electrical shock after unplugging the power supply, X2 capacitor discharge circuitry is required. Usually safety resistors are used to perform this function. Such a solution however brings some disadvantages. The discharge time increases to unacceptable levels for higher X2 capacitor values. The power loss in the discharge resistors needs to be increased in order to decrease X2 capacitor discharge time. As a result, the no load consumption of the application suffers. To avoid this, a special discharge circuitry has been implemented in this design to minimize X2 capacitor discharge time, without impacting no load consumption. This circuit is composed of charge pump R19, R43, R53, D8, D10, D11, C14, C30, C31, transistors Q6, Q8, discharge resistors R16, R22 and auxiliary bias circuitry R1, R21, C1, D1. When the application is plugged into the mains, the charge pump provides voltage to the Q8 MOSFET gate and keeps it turned-on. The drain of MOSFET Q8 pulls down the base of the transistor Q6, which disconnects discharge resistors R16, R22 from the HV input to improve no load efficiency. When the SMPS is disconnected from the mains, the charge pump no longer delivers any current and MOSFET Q8 is turned-off. The auxiliary voltage remains on capacitor C1 and therefore transistor Q6 is turned-on and resisters R16 and R22 discharge the X2 capacitors via the bridge rectifier. The discharge time is shorter than one second. The power consumption of this circuitry is about 6.5 mW for 230 Vac input, a savings of about 86 mW compared to the standard solution with equivalent discharge time. Implementation of the proposed X2 capacitor discharge circuitry also helps to reduce conducted EMI emission because the SMPS designer is less limited by X2 capacitor size vs. discharge time ratio.

The rectified AC line is connected to the PFC front end stage (Figure 3). The PFC stage modulates input current to achieve a high power factor and also to prepare a pre-regulated voltage for the LLC power stage.

Energy is stored in coil L7 when the MOSFET Q4 is turned-on. The energy stored in coil L7 during on time is added to the rectified voltage on capacitor C15 when MOSFET Q4 is turned-off. The bulk capacitors C16 and C17 are thus charged through diode D5. Bulk voltage is divided down by resistors R17, R28, R34, R46 and R63. The emitter follower Q10 is implemented to allow the use of a high impedance divider, which decreases the SMPS standby consumption. The output voltage from this emitter follower is used for two proposes: 1st to prepare skip mode function of the PFC stage and 2nd to provide the LLC controller with information about the bulk voltage (i.e. is it sufficient for operation of the LLC stage or not).

![Figure 2. EMI Filter with X2 Capacitor Discharge Circuitry](http://onsemi.com)
The NCP1605 PFC controller features a skip mode function with thresholds that are fixed to the feedback (FB) regulation level. However, the bulk voltage ripple during skip mode would be too high for the LLC topology. Thus, in this design, the PFC skip mode is implemented via the PFC controller OVP input using external bipolar transistor Q11. The operating frequency of the LLC stage increases when output load diminishes. The LLC stage enters skip mode and disables drivers when load further drops. Transistor Q11 is thus turned-off and resistor R76 is disconnected. The PFC OVP pin voltage thus increases above OVP threshold and PFC stage operation is interrupted. The output voltage then naturally drops and the LLC stage recovers operation – the Q11 is turned-on again and PFC stage operation is enabled as well because resistor R76 pulls down the OVP pin. With this method, the PFC is forced to periodically recharge the bulk capacitor during light load and no load conditions – the PFC skip mode with adjustable bulk voltage ripple is thus implemented. Because the skip mode is implemented externally via the OVP pin rather than via the standby input, it is necessary to bias the STBY pin above 0.3 V using resistor divider R69, R74.

Voltage from the Q10 transistor emitter is also divided down by divider R87, R92, R93 and used to control LLC stage operation via the NCP1397 brown out input. During the PFC stage startup there is no voltage available on the PFC_OK pin of IC3 – the LLC stage thus can not start operation. The PFC_OK pin increases to 5 V after the PFC stage reaches regulation level. Current that is sourced by PFC_OK pin voltage and R83 resistor is added to the current flowing out from resistor R57 and together they create a voltage drop. The LLC stage controller uses this network to protect the application when the bulk voltage drops below the adjusted threshold.

The PFC output voltage is regulated according to information provided to the FB pin. Output voltage is divided down by resistor divider R18, R27, R35, R47, R56, R57 and connected to the FB pin. Filtering capacitor C26 is used because this is a high impedance divider. The bulk voltage compensation network is composed of capacitors C36, C40 and resistor R75. This network also performs soft start when the PFC stage is turned on.

The NCP1605 uses negative current sensing to limit the maximum coil current and to detect the core reset. Current flowing through PFC coil L7 creates a negative voltage on the current sense resistor R38. The PFC controller sources current out of the CS pin in order to maintain a null CS pin voltage. As a result, the CS pin current is directly proportional to the coil current. Resistors R44, R45 are inserted to adjust the CS pin current. When the current...
flowing through inductor $L_7$ and switch $Q_4$ is higher than the maximum current limit level, the CS pin current increases above the OPC threshold (250 uA) and the driver is turned off. The CS input is also used to detect coil demagnetization for zero current detection. The zero current detection prevents the MOSFET from turning on when current flows through the coil. As long as there is no coil current, the NCP1605 operates at a frequency determined by the internal oscillator and external capacitor $C_{38}$. Zero current detection circuitry sensitivity is adjusted by resistor $R_{70}$ and $R_{81}$.

To protect the PFC from sudden drops in the line voltage, the controller monitors the rectified line voltage via brownout divider $R_{15}$, $R_{23}$, $R_{31}$, $R_{50}$, $R_{71}$ and $C_{39}$.

The driver output is connected to MOSFET $Q_4$ via resistors $R_{25}$, $R_{26}$ and diode $D_7$ to regulate turn–on speed. Transistor $Q_7$ is used to speed up the MOSFET turn–off time and thus reduce turn–off losses.

Please refer to the application note AND8281/D for detailed information on the PFC stage design and operation.

Figure 4. The LLC Stage Primary Side Connection

The PFC stage prepares a regulated voltage on bulk capacitors $C_{16}$ and $C_{17}$ for the downstream LLC stage (refer to Figure 3). The LLC stage power loop is closed through $Q_3$ and $Q_5$, transformer $T_{R1}$ and resonant capacitors $C_7$, $C_{18}$ (Figure 4). The NCP1397 LLC controller features a 600 V high–side driver and is capable of driving the HB power stage directly without the use of a driver transformer. Resistors $R_{34}$ and $R_{35}$ are used to suppress ringing and control EMI noise on the power MOSFET gates. Bootstrap capacitor $C_{33}$ provides the energy required for controlling the high side MOSFET. When $Q_5$ is turned–on, the HB pin voltage drops and bootstrap capacitor $C_{33}$ is charged through resistor $R_{96}$ and high–voltage diode $D_{23}$. At turn–on and after any restart, the LLC controller turns on MOSFET $Q_5$ first to charge up the bootstrap capacitor.

The PFC and LLC controllers are powered from the auxiliary winding $W_4$ of transformer $T_{R1}$. The PFC controller charges up the $V_{CC}$ capacitors $C_3$, $C_{42}$ first when the demoboard is plugged into the mains. Once the PFC stage starts operation and the bulk voltage is within the nominal operating range, the LLC stage is enabled. The auxiliary winding also provides bias voltage for the X2 capacitor discharge circuitry via diode $D_1$, resistor $R_1$ and capacitor $C_1$. The X2 capacitor discharge circuitry is described in the PFC Stage section (refer to page 3).

FB Loop and Skip Mode:

The minimum operating frequency of the LLC converter is set by resistor $R_{104}$ (refer to Figure 5). The maximum operating frequency is set by resistor $R_{102}$. The LLC stage
will reach maximum operating frequency during no load conditions.

Feedback is provided by optocoupler OK1. The optocoupler current adjusts the FB voltage applied to the LLC controller. The LLC stage operating frequency is thus modulated to assure output voltage regulation. Resistor R84 is used to limit the maximum voltage excursion on the FB pin in case the LLC controller goes out of the regulation range (like during skip mode or transient loading).

The skip mode function improves the efficiency of the power supply by omitting switching cycles during light load or no load conditions. The skip mode is implemented using the Skip/Disable pin of the LLC controller. The FB pin voltage increases when the load diminishes. Once the load is too low, the LLC stage is not able to maintain regulation because the operating frequency can not increase further (F_{max} clamp – resistor R102). The FB voltage then goes above the V_{fb, max} limit of 5.3 V. The resistor divider R101 and R105 provides the FB pin voltage to the Skip/Fault input. The output drivers are thus automatically turned–off and the device begins to skip switching cycles. For efficient skip mode, the FB voltage should overshoot from 50% to 70% (depends on FB loop response time) of its nominal regulation level. The FB voltage divider R101 = 5.6 kΩ and R105 = 820 Ω was used to allow V_{fb} to swing between 5 – 7.5 V. This setup provides 20 mV pk–pk output voltage ripple during no load conditions.

The Over Current Protection (OCP) is implemented in this design to protect the application from overload conditions. The primary current is sensed indirectly by monitoring the resonant capacitor voltage via the charge pump formed by resistors R42, R52, R64, capacitor C29 and diodes D14, D15 (refer to Figure 6). The charge pump output is loaded by resistor R60 and filtered by capacitor C28. The Soft Start capacitor discharge switch on pin 1 is turned–on once the Fault pin voltage reaches the V_{Ref_fault} threshold (1.04 V). The LLC stage operating frequency is thus automatically increased as the Soft–Start capacitor voltage drops and higher current flows out from the R_{t} pin. The frequency shift naturally reduces the primary current and protects the primary MOSFETs against damage. Also at this time, the I_{timer1} current source is activated on pin 3 and it begins charging external timing capacitor C56. If the overload condition lasts for longer than the time constant set by I_{timer1} current and timer pin components (C56, R103), the controller enters protection mode and output drivers are disabled. Once the timer capacitor C56 is discharged to 1 V, by resistor R103, the application attempts to restart with a Soft Start period. The application can also resume operation with a V_{CC} reset if the LLC controller V_{CC} drops prior to the C56 discharging down to 1 V.

The fault timer duration is too long to protect the application against damage due to a short circuit on the
secondary side (output terminals short or secondary transformer winding short). To protect against this possibility, there is a second OCP comparator monitoring the fault pin voltage. When the frequency shift (via Soft Stat pin and resistors R_{07}, R_{1(0)} is no longer sufficient to keep the primary current limited, the resonant capacitor voltage increases up to such a level that the fault input voltage reaches the V\text{ref, OCP} threshold (1.55 V). The application then latches off and protects the power stage components from damage. The circuit remains latched until the VCC is cycled down below V\text{CC, reset} and then back above the V\text{CC, on} threshold.

The primary current level that will activate the overload protection is given by the maximum secondary current transformed to the primary side and also by the transformer magnetizing current. The RMS value of primary current can be approximately calculated using Equation 1.

\[
I_{\text{primary, rms}} \approx \sqrt{\frac{1}{8} \left( I_{\text{out, max}}^2 \cdot \pi^2 \cdot G_{\text{nom}}^2 + \frac{V_{\text{bulk, nom}}^2}{24 \cdot L_{m}^2 \cdot f_{\text{op, ovd}}} \right)^2}
\]  

(eq. 1)

Where:

- \( I_{\text{out, max}} \) is the maximum output current of the LLC stage (23 A)
- \( G_{\text{nom}} \) is the nominal LLC stage gain (\( G_{\text{nom}} = 0.062 \) – refer to Page 13)
- \( V_{\text{bulk, nom}} \) is the nominal bulk voltage
- \( L_{m} \) is the primary magnetizing inductance (715 \( \mu \text{H} \))
- \( f_{\text{op, ovd}} \) is the operating frequency during overload conditions (78 kHz)

The above equation is an accurate approximation for applications operating at resonant frequency. Accuracy decreases for applications operated far below or above series resonant frequency. The most accurate approach is to measure primary RMS current either from simulation or directly in the application. For the application at hand, the primary RMS current level is 1.68 A when output power is 276 W (i.e. 115% of nominal output power). The primary current flows through the resonant capacitor and creates an ac voltage \( V_{\text{Cs, ac}} \) that is given by Equation 2.

\[
V_{\text{Cs, ac}} = \frac{I_{\text{primary, rms}} \cdot L_{m} \cdot 2 \cdot \pi \cdot f_{\text{op, ovd}}}{2 \cdot \pi \cdot f_{\text{op, ovd}} \cdot C_{\text{Cs}}} = \frac{1.68}{2 \cdot 3.14 \cdot 78 \cdot 10^3 \cdot 30 \cdot 10^{-9}} = 114 \text{ Vac}
\]

Where:

- \( C_{\text{Cs}} \) is the resonant capacitor value (i.e. \( C_{7}+C_{18} \))

The DC offset, that is present on the resonant capacitor, is not transferred to the Fault pin as the charge pump cannot handle DC voltages.

A critical failure (like short circuit) can cause the resonant capacitor voltage to swing above the nominal bulk voltage. High peak current can then flow through the charge pump diodes \( D_{14}, D_{15} \). The series resistors \( R_{42}, R_{52} \) limit the charge pump diode current to a safe level. The total series resistance can be approximately calculated using Equation 3.

\[
R_{s} = \frac{V_{\text{Cs, peak}}}{I_{\text{f, limit}}} = \frac{1 \cdot 10^3}{20 \cdot 10^{-3}} = 50 \text{ k}\Omega \quad \text{(eq. 3)}
\]

Where:

- \( R_{s} \) is the total series resistance to be used (\( R_{42}+R_{52} \))
- \( V_{\text{Cs, peak}} \) is the peak resonant capacitor voltage
- \( I_{\text{f, limit}} \) is the maximum forward current of \( D_{14}, D_{15} \)

The final application uses a series resistance of \( R_{s} = R_{42} + R_{52} = 48 \text{ k}\Omega \). The load resistance of 1 k\( \Omega \) (\( R_{60} \)) has been implemented to assure good noise immunity on the Fault pin and resistors \( R_{42}, R_{52} \) need to be verified (Equation 5).

\[
R_{s} = \frac{2 \cdot \pi \cdot f_{\text{op, ovd}} \cdot R_{60} \cdot (R_{60}+R_{64})^2}{5 \cdot 2 \cdot R_{60} \cdot (R_{42}+R_{52})^2} = 68 \text{ nF} \quad \text{(eq. 5)}
\]

The total power loss generated in the series combination of resistors \( R_{42}, R_{52} \) needs to be verified (Equation 6).

\[
P_{R_s} = \left( \frac{\pi \cdot V_{\text{ref, fault}} \cdot 0.9}{2 \cdot R_{60}} \right)^2 \cdot R_s = 0.208 \text{ W} \quad \text{(eq. 6)}
\]
As already mentioned, the first fault comparator threshold is reached when the overload conditions occur. The Soft–Stat capacitor discharge switch is activated and the operating frequency of the converter is automatically increased, limiting the primary current. The series resistor $R_97 = 5.6 \, \text{kΩ}$ is used on the Soft–Start input to overcome erratic oscillations during transition between normal and overload operating modes. This resistor also decreases the maximum operating frequency during the overload conditions to 150 kHz.

A startup frequency of 200 kHz has been chosen for this design to limit the primary current during the Soft–Start phase. The startup frequency is given by the total current sourced from the $R_t$ pin during startup. When the application starts up both the PFC and LLC controllers reach operating $V_{CC}$ voltage. The LLC controller is disabled via brownout input until the PFC stage output reaches regulation level. The Soft Start capacitor discharge switch is active during this time period as well as the $R_t$ pin reference voltage source. The soft start capacitor thus charges to the voltage that is given by the $R_t$ pin reference voltage (2.3 V) and resistor divider composed of resistors $R_97$, $R_{100}$. The Soft–Start capacitor initial voltage can be calculated using Equation 7.

$$V_{SS\text{-start}} = 2.3 \cdot \frac{R_97}{R_97 + R_{100}} = \frac{5.6}{5.6 + 6.2} = 1.1 \, \text{V} \quad \text{(eq. 7)}$$

The internal resistance of the Soft start switch can be neglected as its value is small at 100 Ω. When the LLC controller reaches operating $V_{CC}$ prior to the BO_OK signal, the startup frequency can be calculated using the serial and parallel combination of resistors $R_97$, $R_{100}$ and $R_{104}$. The total $R_t$ pin resistance during Soft–Start is calculated using Equation 8.

$$R_{Rt\text{-start}} = \frac{R_{104} \cdot (R_97 + R_{100})}{R_{104} + R_97 + R_{100}} \quad \text{(eq. 8)}$$

For a 200 kHz startup frequency, a $R_{Rt\text{-start}}$ value of 8.47 kΩ is required (refer to the NCP1397A/B datasheet – $f_{\text{op vs. } R_{Rt\text{-chart}}}$).

The value of resistor $R_{100}$ can be calculated by rearranging Equation 8 to Equation 9.

$$R_{100} = \frac{R_{Rt\text{-start}} \cdot R_{104} + R_{Rt\text{-start}} \cdot R_97 - R_97 \cdot R_{104}}{R_{104} - R_{Rt\text{-start}}} = 6.2 \, \text{kΩ} \quad \text{(eq. 9)}$$

The Soft–Start capacitor value is given by the required output voltage ramp–up time. The Soft–Start capacitor, $C_{55} = 1 \, \mu\text{F}$, in combination with $R_{100}$ resistor provide output voltage ramp–up time of 18 ms.

During an overload condition, the fault timer is activated to turn–off the application after a programmed time period. This technique prevents the SMPS from thermal damage. If the overload condition disappears before the timer expires, the controller doesn’t interrupt operation. The fault timer duration is given by capacitor $C_{56}$, resistor $R_{103}$ and $C_{\text{timer}}$ pin charging current $I_{\text{timer1}}$. The fault timer capacitor charging time can be calculated using Equation 10. The charging period should be selected such that there is enough margin for the Soft–Start period and transient overloading. A fault period of 100 ms has been used in this design.

$$T_{\text{fault}} = -R_{103} \cdot C_{56} \cdot \ln \left( 1 - \frac{V_{\text{timer(on)}}}{R_{103} \cdot I_{\text{timer1}}} \right) = \frac{4}{150 \cdot 10^3 \cdot 175 \cdot 10^{-6}} = 117 \, \text{ms} \quad \text{(eq. 10)}$$

Where:

$V_{\text{timer(on)}}$ is the fault timer upper threshold

$I_{\text{timer1}}$ is the timer pin charging current

The off–time period of the fault timer is given by Equation 11 when the LLC controller $V_{CC}$ stays at sufficient level (i.e. above $V_{CC\text{-off}}$).

$$T_{\text{off}} = R_{103} \cdot C_{56} \cdot \ln \left( \frac{V_{\text{timer(on)}}}{V_{\text{timer(off)}}} \right) = 150 \cdot 10^3 \cdot 4.7 \cdot 10^{-6} \cdot \ln \left( \frac{4}{175} \right) = 977 \, \text{ms} \quad \text{(eq. 11)}$$

Where:

$V_{\text{timer(off)}}$ is the fault timer lower threshold

The recovery time should be selected with respect to the thermal stress of the power stage components. The timer duration is determined by the $V_{CC}$ capacitor discharge time in this design. This is because the primary controller supply voltage naturally drops when the LLC stage is turned–off. In this application, the SMPS recovery time is 1.8 s.

The PCB design features options for over current protection diodes $D_6$, $D_9$. Protection diodes, when implemented, limit the maximum resonant capacitor voltage excursion to $V_{bulk}$ level. The primary current is thus naturally limited to a safe level. The use of protection diodes when making changes to the demoboard circuitry is recommended. The OCP diodes can be removed again after the modified system is verified to be working correctly.
The secondary side uses synchronous rectification with a center tapped transformer configuration in order to provide high efficiency full wave rectification (Figure 7). The SR MOSFETs Q2, Q9 are connected in series with secondary windings W2, W3, inductors L1, L8, filtering capacitor bank C8−C11, C21−C24. Standard TO-220 package SR MOSFETs have been selected for the application because they reduce manufacturing costs. However, the parasitic inductances of the SR MOSFET package create an error voltage that increases the turn off current threshold. The shift in turn off threshold results in a less than optimal conduction period, reducing the efficiency. In order to avoid this unwanted shift, the NCP4303 features a package parasitic inductance compensation technique. The technique requires the use of a small compensation inductance (L1, L8). The secondary current creates a voltage on the compensation inductance and dynamically offsets the ZCD comparator threshold via the COMP input. This method assures maximum conduction time of the SR MOSFET and therefore increases efficiency. The compensation inductance value is approximately 4 nH.

SR controllers IC1, IC2 are powered from the application output. Resistors R10, R32 together with decoupling capacitors C5, C6, C19 and C20 form RC filters to smooth current spikes created during SR driver turn–on. The current sense input monitors the SR MOSFET drain voltage to determine when to turn on and off the SR MOSFET. The NCP4303 driver is connected directly to the SR MOSFET without any external gate resistor in order to minimize turn–off delay. No ringing or EMI issues related to driver current occur assuming a proper layout is used i.e. driver circuitry loop area is minimized.

The power losses related to the SR MOSFET gate driving can be calculated using Equation 12.

\[ P_{\text{DRV}} = V_{\text{CC}} \cdot V_{\text{clamp}} \cdot C_{g_{\text{ZVS}}} \cdot f_{\text{sw}_{\text{max}}} \]  

(eq. 12)

Where:
- \( V_{\text{CC}} \) is the NCP4303 supply voltage (Vout in this case)
- \( V_{\text{clamp}} \) is the driver clamp voltage
- \( C_{g_{\text{ZVS}}} \) is the gate to source capacitance of the SR MOSFET in ZVS mode
- \( f_{\text{sw}_{\text{max}}} \) is the maximum switching frequency of the application

The SR MOSFET conduction losses can be calculated from the secondary RMS current and channel resistance for a given gate voltage (Equation 13).

\[ P_{\text{COND}} = \left( \frac{I_{\text{out}}}{4} \right)^2 \cdot R_{\text{DS(on)}}@V_{\text{g}_{\text{clamp}}} \]  

(eq. 13)

Where:
- \( I_{\text{out}} \) is the output current
RDS(on) at Vgs_clamp – is the SR MOSFET channel resistance for the given driver voltage clamp level

The body diode conduction time and related losses can be significantly reduced due to the NCP4303 compensation capability. If the body diode losses are neglected, the total losses of the SR system can be approximated by summing the driving and conduction losses and then multiplying by the number of SR MOSFETs (Equation 14).

\[
P_{SR} = 2 \cdot (P_{COND} + P_{DRV}) 
\]

(Eq. 14)

The SR MOSFET selection has been made with both cost and efficiency considerations. Another important step is selecting which NCP4303 driver clamp version to use (6 V or 12 V). The choice can be made using the above equations. The theoretical power losses calculated for a SR system using IRFB3206 MOSFETs and two different gate driver clamp voltages can be seen in Figure 8.

Figure 8 shows that theoretically calculated losses increase for output current lower than 14 A when 12 V gate driver clamp is used. The maximum efficiency requirement is specified at 50% of full load by the 80 PLUS @ program. Therefore the NCP4303B (6 V gate drive clamp) has been selected due to its improved efficiency at light to medium load.

The power dissipation within the IC package needs to be considered in order to avoid overheating issues. Losses related to the driving of the SR MOSFET gate can be calculated using Equation 15.

\[
P_{DRV, IC} = \frac{1}{2} C_{g,ZVS} \cdot V_{clamp}^2 \cdot f_{SW} \cdot \left( \frac{R_{drv, low eq}}{R_{drv, low eq} + R_{g,int}} + C_{g,ZVS} \cdot V_{clamp} \cdot f_{SW} \cdot \left( V_{CC} - V_{clamp} \right) + \frac{1}{2} C_{g,ZVS} \cdot V_{clamp}^2 \right) \cdot f_{SW} \cdot \left( \frac{R_{drv, high eq}}{R_{drv, high eq} + R_{g,int}} \right) = 76 \text{ mW} 
\]

(Eq. 15)

Where:
R_{drv, low eq} – is the SR driver low side switch equivalent resistance (1.55 \Omega)
R_{drv, high eq} – is the SR driver high side switch equivalent resistance (7 \Omega)
R_g_{int} – is the internal gate resistance of the SR MOSFET

Power losses related to the SR controller internal consumption are given by Equation 16.

\[
P_{ICC} = V_{CC} \cdot I_{CC} = 35 \text{ mW} 
\]

(Eq. 16)

Where:
I_{CC} – is the NCP4303 driver supply current for C_{load} = 0 nF and maximum operating frequency (refer to the NCP4303 datasheet for the I_{CC} versus f_{op} chart).

The DIE temperature is given by the thermal resistance from junction to ambient, total power dissipation of the SR controller, and ambient temperature (Equation 17).

\[
T_{DIE} = \left( P_{DRV, IC} + P_{ICC} \right) \cdot R_{JA} + T_A = (0.076 + 0.035) \cdot 180 + 60 = 80^\circ C 
\]

(Eq. 17)

Where:
R_{JA} – is the IC thermal resistance from junction to ambient
T_A – is the ambient temperature (worst case when the board is fully loaded)

High DIE temperature could appear in applications with high operating frequencies. Additional copper heat sinking in the PCB or a thermal conductor between the SR controller and SMPS package should be used to maintain DIE temperature below the maximum ratings.

The snubber networks R_8, R_9, R_{40}, R_{41}, C_4 and C_{25} dampen the voltage ringing that occurs on the SR MOSFET drain when the secondary winding voltage reverses. The ringing frequency is given by the secondary leakage inductance L_{sec,leak} and output capacitance C_{oss} of the SR MOSFET. The snubber resistance should be equal to the characteristic impedance of the ringing circuitry in order to effectively dampen the oscillations Reference 9, (Equation 18).

\[
R_{snubber} = \sqrt{\frac{L_{sec,leak}}{C_{oss}}} 
\]

(Eq. 18)

Where:
R_{snubber} – is the snubber resistance
L_{sec,leak} – is the secondary leakage inductance
C_{oss} – is the SR MOSFET output capacitance

The snubber capacitance C_{snubber} must be larger than the SR MOSFET output capacitance, but small enough to minimize dissipation in the snubber resistor. The snubber capacitance is generally chosen to be at least 3 to 4 times higher than the value of the parasitic resonant capacitor.

\[
C_{snubber} = 3 \rightarrow 4 \cdot C_{oss} 
\]

(Eq. 19)

The NCP4303 minimum on time and off time generators protect against unwanted switching that could be triggered by ringing on the ZCD comparator. Resistors R_{11}, R_{39} set the minimum on time period. The minimum on time period is selected based on the maximum operating frequency of the LLC stage as well as the secondary current waveform.
During light load conditions, the secondary current oscillation can cause unwanted SR MOSFET switching. A minimum on time of 1.1 μs is needed to prevent this behavior. The required value of min Ton adjust resistors can be calculated using Equation 20.

\[ R_{T_{on\_min}} = \frac{T_{on\_min} - 4.66 \cdot 10^{-8}}{9.82 \cdot 10^{-11}} \]

\[ = \frac{1.1 \cdot 10^{-6} - 4.66 \cdot 10^{-8}}{9.82 \cdot 10^{-11}} = 11 \text{kΩ} \]  

(eq. 20)

Where:

*R_{T_{on\_min}}* is the minimum on time adjust resistor

The minimum off time is given by resistors R7, R37. To prevent issues when the application operates at minimum frequency, the minimum off time should be set to as long as possible. However, the minimum off time value is limited by the maximum operating frequency clamp. In our case, the minimum switching period of the LLC stage is 9.1 μs. Thus the minimum off time period is selected to be 3.9 μs in order to provide a long minimum off time with some margin for the minimum switching period. The minimum off time adjust resistor value can be calculated using Equation 21.

\[ R_{T_{off\_min}} = \frac{T_{off\_min} - 5.4 \cdot 10^{-8}}{9.56 \cdot 10^{-11}} \]

\[ = \frac{3.9 \cdot 10^{-6} - 5.4 \cdot 10^{-8}}{9.56 \cdot 10^{-11}} = 39 \text{kΩ} \]  

(eq. 21)

Where:

*R_{T_{off\_min}}* is the minimum off time adjust resistor

If the LLC converter uses a very wide operating frequency range, it is beneficial to modulate the minimum off time period. The modulation is possible using a resistor connected from the SR MOSFET drain to the opposite SR controller min Toff pin. When the drain voltage is at a high level, current is injected into the min Toff pin. The internal capacitance charging current is thus decreased and the minimum off time period increases. Please refer to the NCP4303 datasheet for more information on how to modulate the minimum off time period.

The NCP4303 features a trigger input that can be used to implement synchronous rectification systems in CCM applications. Additionally, the trigger input can be used to disable the IC and activate a low consumption standby mode. The demoboard layout features optional circuitry (refer to complete schematic – page 31) that allows the customer to implement a primary triggering signal. Normally this is not needed in LLC applications as the NCP4303 features a low propagation delay from the CS input to the DRV output. The trigger circuitry option is implemented to allow the customer to test the trigger input functionality.

The no load consumption of the application can be reduced by implementing parallel Schottky diodes across the SR MOSFETs and turning the SR system into sleep mode during light load. The demoboard provides a control input that can be used for this purpose. The external SR standby on/off circuitry can be implemented by monitoring output current.

It is critical to assure correct layout of the SR system to avoid issues with the zero current detection circuitry. Please refer to the NCP4303 datasheet for layout considerations and more information on how the ZCD and the compensation systems work.

The secondary filtering capacitor bank RMS current during full load series resonant frequency operation can be calculated using Equation 22.

\[ I_{C/\text{RMS}} = I_{\text{out\_nom}} \cdot \sqrt{\frac{3^2}{8} \cdot 1} = 20 \cdot 0.483 = 9.7 \text{ A} \]  

(eq. 22)

Where:

*I_{\text{out\_nom}}* is the nominal output current

Filtering capacitors must be used in parallel to handle the total RMS current. Low impedance type capacitors have been used in this design. The total equivalent series resistance (ESR) of the capacitor bank is 2.25 mΩ. The output voltage ripple related to the filtering capacitor bank is composed from two components:

1st the ESR related ripple (Equation 23) and

2nd the ripple related to the capacitor bank capacitance (Equation 24).

\[ V_{Cf\_ripple\_pk-pk} = ESR \cdot I_{\text{rect\_peak}} = 2.2 \cdot 10^{-3} \cdot \frac{\pi}{2} \cdot 20 = 69 \text{ mV} \]  

(eq. 23)

Where:

*I_{\text{rect\_peak}}* is the peak current through the secondary

\[ V_{\text{out\_ripple\_cap\_pk-pk}} = \frac{I_{\text{out\_nom}}}{2 \cdot \sqrt{3} \cdot \pi \cdot f_{\text{op\_nom}} \cdot C_f} \]  

(eq. 24)

\[ \cdot (\pi - 2) = \frac{20}{2 \cdot \sqrt{3} \cdot 80 \cdot 10^3 \cdot 8 \cdot 10^{-9}} \cdot (\pi - 2) = 10 \text{ mV} \]

Where:

*f_{\text{op\_nom}}* is the nominal operating frequency

*C_f* is the total capacitance of the capacitor bank

The capacitive component of the output ripple is negligible in this case because of the total filtering capacitance value.

The power losses that are created by the filtering capacitor bank ESR can be calculated using Equation 25.

\[ P_{C/\text{ESR}} = \left( I_{\text{out\_nom}} \cdot \sqrt{\frac{3^2}{8} - 1} \right)^2 \cdot ESR = \]  

(eq. 25)

\[ = \left( 20 \cdot \sqrt{\frac{3^2}{8} - 1} \right)^2 \cdot 2.25 \cdot 10^{-3} = 0.21 \text{ mW} \]

The PCB secondary side layout can significantly affect current distribution among the filtering capacitors. Ideally, the secondary layout should result in an equal distribution of
filtering capacitor connection series parasitic impedances (refer to Figure 9). If mismatched, capacitors with lower series impedance within the bank handle a higher current, which results in decreased life time.

Figure 9. Ideal Configuration of the Capacitor Bank

The capacitor bank provides the bulk of filtering for the secondary currents, but it does not fully filter out narrow glitches produced when the secondary winding reverses. Thus an additional LC filter (L2, C12) has been implemented. The resonant frequency of this filter should be as low as possible but on the other hand it can affect system loop gain if selected too close to the crossover frequency. A resonant frequency of 24 kHz has been selected for this design. The filter inductor of 200 nH features a low DC resistance, which helps keep efficiency high at medium and full load conditions. A filtering capacitor C12 of 220 μF (low impedance type) has been implemented. The filter provides higher peaking around the resonant frequency when a low ESR capacitor is used. On the other hand, if a capacitor with too high of ESR is used, the output voltage drop during fast transient loading increases. The additional LC filter also reduces output voltage ripple at nominal operating frequency and full load conditions by −10 dB.

The output voltage regulation is assured by IC4. Divider R89, R98 and R99 provides the regulator IC with output voltage information. Resistor R85 limits the maximum current that can pass through optocoupler OK1. Resistor R90 bypasses the optocoupler and provides a bias path for IC4. The compensation network is composed of resistor R95 and capacitors C49, C51. Please refer to application note AND8327/D to learn how to calculate the compensation network. The Bode plot of the full loaded LLC stage is shown in Figure 10.

Figure 10. Closed Loop Gain and Phase of the LLC Power Stage for Nominal Output Current

As previously mentioned, the secondary RMS currents are quite high in this application. Parasitic layout resistances can thus affect the LLC stage efficiency. A PCB with 70 μm copper plating has been used for this demo board to minimize power losses related to the secondary side layout.

Resonant tank and transformer design:

An LLC transformer from Pulse engineering has been selected for this design. This transformer offers extra high leakage inductance thanks to a special bobbin arrangement (see demo board photo in Figure 63). The transformer leakage inductance is used as a resonant inductance. This solution eliminates the need for an additional resonant inductor, reducing the overall application cost. On the other hand, a transformer with high leakage inductance causes a stronger proximity effect in the windings, resulting in increased requirements for the winding construction. Another disadvantage of the leaky transformer is high stray flux that negatively impacts the radiated EMI emission. Significant eddy currents can be induced by stray flux in the surrounding metal parts. Therefore it is important to not place these parts too close to the transformer.

The transformer is designed in such a way that the LLC stage is operated in, or very close to, the series resonant frequency (fS) for full load conditions and nominal bulk voltage. Efficiency is optimized for these operating conditions. The LLC stage operating frequency is increased up to 110 kHz to maintain output voltage regulation when the load diminishes. When the output load drops further down below 1.4 A, the maximum operating frequency clamp is reached and the application enters skip mode operation to reduce the LLC stage power losses. On the other
hand, when the bulk voltage drops, the secondary regulator decreases the LLC stage operating frequency down to 65 kHz to achieve the necessary gain for output voltage regulation.

First harmonic approximation (FHA, refer to References 7 or 11) is a common method for resonant converter analysis. In the actual application, the resonant tank is driven by a square wave voltage. However, FHA modeling does not use a square wave drive. Instead, an equivalent load resistance is used for FHA analysis to compensate for the difference (Equation 26):

\[ R_{ac} = \frac{8}{\pi^2} \cdot \frac{V_{\text{out}}}{I_{\text{out,nom}} \cdot \eta} = 0.51 \quad (\text{eq. 26}) \]

Where:
- \( R_{ac} \) – is the equivalent load resistance for the FHA model
- \( \eta \) – is expected efficiency of the LLC stage (94.5%) The FHA equivalent schematic of an LLC stage with external resonant inductor \( L_s \) and standard transformer with magnetizing inductance \( L_m \) and negligible leakage inductance can be seen in Figure 11.

**Figure 11. Equivalent Schematic for FHA Analysis**

The LLC converter behaves like a frequency dependent divider i.e. the power stage gain can be modified by changing the operating frequency. The LLC stage gain needed for output voltage regulation under full load conditions and selected bulk voltage range (350 Vdc – 425 Vdc) can be calculated based on Equations 27 – 29.

\[ G_{\text{min}} = \frac{2 \cdot \left( V_{\text{out}} + V_{\text{f,SR}} \right)}{V_{\text{bulk,nom}}} = \frac{2 \cdot (12 + 0.2)}{395} = 0.057 \quad (\text{eq. 27}) \]

\[ G_{\text{nom}} = \frac{2 \cdot \left( V_{\text{out}} + V_{\text{f,SR}} \right)}{V_{\text{bulk,nom}}} = \frac{2 \cdot (12 + 0.2)}{395} = 0.0618 \quad (\text{eq. 28}) \]

\[ G_{\text{max}} = \frac{2 \cdot \left( V_{\text{out}} + V_{\text{f,SR}} \right)}{V_{\text{bulk,nom}}} = \frac{2 \cdot (12 + 0.2)}{350} = 0.0697 \quad (\text{eq. 29}) \]

Where:
- \( V_{\text{f,SR}} \) – is the expected average drop of the SR rectifier including the secondary layout drop
- \( V_{\text{bulk,max}} \) – is the maximum operating bulk voltage
- \( V_{\text{bulk,nom}} \) – is the nominal operating bulk voltage
- \( V_{\text{bulk, min}} \) – is the minimum operating bulk voltage

The resonant tank characteristic impedance (Equation 30) and quality factor (Equation 31) affect the operating frequency range requirement for output voltage regulation.

\[ Z_0 = \sqrt{\frac{L_s}{C_s}} \quad (\text{eq. 30}) \]

Where:
- \( L_s \) – is the resonant inductor value
- \( C_s \) – is the resonant capacitor value

\[ Q = \frac{n^2 \cdot R_{ac}}{Z_0} \quad (\text{eq. 31}) \]

The lower the resonant capacitor value, the higher the resonant inductance needs to be in order to assure nominal operating frequency. A higher resonant inductance value generally results in a more narrow operating frequency range throughout the line and load conditions. It is always beneficial to keep a narrow operating frequency range to optimize efficiency and EMI performance.

Based on the above considerations, it is evident that the resonant tank with minimized resonant capacitance provides optimum performance. However, the resonant capacitor voltage can reach unacceptable levels if the resonant capacitance value is too low. It is beneficial to limit the resonant capacitor voltage excursion to a level that is below nominal bulk voltage level. There are three main reasons for this consideration:

1st the lower voltage ratings for the resonant capacitor
2nd less voltage stress for the PCB
3rd simple OCP circuitry can be implemented using clamping diodes (D6 and D9 options in demoboard PCB).

The nominal resonant capacitor RMS current can be approximated using Equation 32.

\[ I_{\text{Cs,RMS,nom}} \approx I_{\sec,RMS,nom} \cdot G_{\text{nom}} = \frac{\pi}{2 \cdot \sqrt{2}} \cdot I_{\text{out,nom}} \cdot G_{\text{nom}} = \frac{\pi}{2 \cdot \sqrt{2}} \cdot 20 \cdot 0.062 = 1.38 \text{ A} \]

Where:
- \( I_{\text{out,nom}} \) – is the nominal output current

The above calculation does not include magnetizing current because it has only a minor impact. The resonant capacitor capacitance can now be calculated based on the selected capacitor peak voltage (Equation 33).

\[ C_s = \frac{I_{\text{Cs,RMS,nom}} \cdot \sqrt{2}}{2 \cdot \pi \cdot f_{\text{op,nom}} \cdot \left( V_{\text{Cs,peak,nom}} - \frac{V_{\text{bulk,nom}}}{2} \right)} \quad (\text{eq. 33}) \]

\[ = \frac{1.38 \cdot \sqrt{2}}{2 \cdot \pi \cdot 80 \cdot 10^3 \cdot \left( 320 - 395 \right)} = 31.6 \text{ nF} \]
Practically there are two possible choices for implementing the resonant capacitor:

a) one resonant capacitor of 33 nF
b) two resonant capacitors of 15 nF

Variant b) has been selected for this design i.e. two 15 nF capacitors (C7 and C18 in Figure 6). The advantage of this solution is that the primary current divides equally between two capacitors and the bulk capacitor ripple current is reduced by 30%.

The resonant inductance value can be calculated from the selected nominal operating frequency using rearranged Thompson law (Equation 34). A nominal operating frequency of 80 kHz was selected for this application.

$$L_s = \frac{1}{C_s \cdot \left(2 \cdot \pi \cdot f_s\right)^2} = \frac{1}{30 \cdot 10^{-9} \cdot \left(2 \cdot \pi \cdot 80 \cdot 10^3\right)^2} = 131.9 \ \mu H \approx 130 \ \mu H$$  \hspace{1cm} (eq. 34)

Where:

- $f_s$ – is the series resonant frequency ($f_s = f_{op, nom}$ in our case)

The magnetizing inductance of the future transformer should be selected with respect to the LLC stage operating frequency range. The operating frequency range is reduced when a high magnetizing inductance value is used. On the other hand, the maximum gain of the LLC stage is reduced and the magnetizing current is not sufficient to overcharge the total bridge capacitance and maintain a ZVS condition when the magnetizing inductance value is too high. The maximum magnetizing inductance value that will still assure ZVS during no load conditions can be calculated based on the selected deadtime period, maximum operating frequency and total bridge capacitance (Equation 35). The bridge capacitance is composed of the primary MOSFETs output capacitances and the primary layout parasitic capacitance.

$$L_{m, max} = \frac{DT}{8 \cdot f_{op, max} \cdot C_{HB, total}} = \frac{350 \cdot 10^{-9}}{8 \cdot 110 \cdot 10^3 \cdot 360 \cdot 10^{-12}} = 1.1 \ mH$$  \hspace{1cm} (eq. 35)

Where:

- $DT$ –is the selected deadtime period (350 ns for this design)
- $f_{op, max}$ –is the maximum operating frequency
- $C_{HB, total}$ –is the total bridge parasitic capacitance ($2 \cdot C_{oss} + C_{layout}$)

The primary RMS current increases if too low of magnetizing inductance value is used. Increased RMS current results in higher losses generated in the transformer and primary MOSFETs. The magnetizing to resonant inductance ratio of $k = L_m / L_s = 5.5$ has been chosen for this design as a compromise between losses generation and LLC stage operating frequency range. Magnetizing inductance can be calculated using Equation 36.

$$L_m = k \cdot L_s = 5.5 \cdot 130 \cdot 10^{-6} = 715 \ \mu H \hspace{1cm} (eq. 36)$$

Where:

- $k$ – is the ratio between magnetizing and resonant inductance

All of the above calculations have been performed with the expectation that the application will operate at the series resonant frequency for nominal load (20 A) and bulk voltage (395 Vdc). The nominal gain of an LLC converter, that features external resonant inductance $L_s$, a transformer with negligible leakage inductance ($L_{lk} \rightarrow 0$), and primary inductance $L_{primary} = L_m$, is equal to the inverse of the transformer turns ratio when operated at series resonant frequency (Equation 37).

$$G_{nom} = \frac{1}{n_{discrete}} = \sqrt{\frac{L_{secondary}}{L_{primary}}} = \frac{2 \cdot \left(V_{out} + V_f\right)}{V_{bulk, nom}} = \frac{2 \cdot (12 + 0.2)}{395} = 0.0618$$  \hspace{1cm} (eq. 37)

Where:

- $L_{primary}$ – is the primary inductance measured with secondary winding opened
- $L_{secondary}$ – is the secondary inductance measured with primary winding opened
- $n_{discrete}$ – is the transformer turns ratio for the LLC design with external resonant coil

Required secondary inductance can then be calculated using Equation 38.

$$L_{secondary} = L_{primary} \cdot G_{nom}^2 = 715 \cdot 10^{-6} \cdot 0.0618^2 = \frac{2.73 \ \mu H}{eq. 38}$$

A simulation model can be built to verify the full load gain characteristic of the proposed LLC design with external resonant inductor (Figure 12). A transformer with high coupling coefficient is expected => coupling $\rightarrow 1$.

**Figure 12. Simulation Model for the LLC Stage with External Resonant Inductance**
The simulated full load gain characteristic in Figure 13 shows that the proposed design will work in series resonant frequency for full load and nominal bulk voltage conditions.

The difference between the LLC design with external resonant inductance and the design that uses a transformer with high leakage inductance can be determined with simulations. The integrated resonant tank gain differs from the inversed transformer turns ratio when operated in series resonant frequency. This phenomenon is related to the fact that the leakage inductance is physically not located in series with the primary winding like in the external resonant coil solution. The gain of the LLC design with integrated resonant tank, that uses transformer with primary inductance \( L_{\text{primary}} = L_m \), leakage inductance \( L_{\text{leakage}} = L_s \) and secondary to primary turns ratio \( n_{\text{disc}} \), is thus higher than the inversed turns ratio for the discrete solution when operated at series resonant frequency (Equation 39).

\[
G_{\text{nom, integrated}} > \frac{1}{n_{\text{disc}}} \tag{eq. 39}
\]

Figure 14 shows the simulated gain characteristics comparison for both solutions.

The primary to secondary turns ratio has to be increased by coupling coefficient to assure the same nominal gains at series resonant frequency for both LLC resonant tank solutions. The new turns ratio of the design with integrated leakage inductance is defined by Equation 40.

\[
n_{\text{integrated}} = \frac{n_{\text{disc}}}{\sqrt{1 - \frac{L_s}{L_m}}} = \frac{16.18}{17.88} = 0.907 \tag{eq. 40}
\]
Where:

\[ L_s = L_{lk\_primary} \] is the primary inductance measured with secondary winding shorted

\[ L_m = L_{primary} \] is the primary inductance measured with secondary winding opened

A SPICE model of the modified integrated resonant tank can be seen in Figure 15.

![Figure 15. Simulation Model of the LLC Stage with Integrated Resonant Tank and Modified Turns Ratio](image)

Simulation results from Figure 16 show that the nominal gains for both solutions are the same when the operating frequency is equal to the resonant frequency. The modified integrated resonant tank solution also provides higher gain below series resonant frequency. This is beneficial as the operating frequency range will be reduced compared to the LLC design with external resonant coil.

The calculated resonant tank components are as follows:

- Resonant capacitor: \( C_s = 2 \times 15 \text{ nF} \)
- Transformer with divided bobbin:
  \[ L_{primary} = 715 \mu\text{H} \]
  \[ L_{secondary} = \frac{L_{primary}}{n_{\text{integrated}}^2} = 2.23 \mu\text{H} \]
  \[ L_{lk\_primary} = 130 \mu\text{H} \] when secondary winding is shorted

The transient simulation results for the proposed LLC resonant tank design are shown in Figure 17. Bulk voltage of 395 Vdc and output load of 20 A have been applied during this simulation. The results show that the output voltage is regulated to the target level i.e. 12 Vdc when the application works at a frequency of 80.3 kHz, which meets the target resonant frequency (80 kHz).
The number of primary turns needs to be calculated with respect to the transformer flux density excursion. Maximum flux density will be reached for the minimum operating frequency and maximum bulk voltage (Equation 41).

\[
N_p = \frac{V_{bulk} - \Delta B_{max} \cdot f_{SW_{min}} \cdot A_e}{8} = 38 \text{ turns (eq. 41)}
\]

Where:
- \( B_{max} \) – is the selected peak flux density
- \( f_{SW_{min}} \) – is the minimum operating frequency clamp
- \( A_e \) – is the effective area of the ferrite core center leg cross section

A ferrite core with air gap on the center leg has to be used to allow for primary inductance adjustment. The air gap stores most of the magnetizing energy related to the primary winding. Thus it is beneficial to place the air gap below the primary winding to minimize additional stray flux and reduce the proximity effect.

The air gap position within the bobbin affects primary and secondary inductance values. Generally, the inductance of an inductor with gapped ferrite core is lower when the gap is located below the coil winding rather than outside of the winding. The difference between both cases is due to the magnetic flux bulging out from the gap and coil. When the air gap is not located under the coil winding there will be higher stray flux – refer to Figure 18.
Figure 19. Transformer with Divided Bobbin and Air Gap Below Primary Winding

\[ N_p = \sqrt{\frac{L_{primary}}{N_p^2}} \]  
(eq. 42)

\[ \Lambda_{secondary} = \frac{L_{secondary}}{N_s^2} \]  
(eq. 43)

\[ \Lambda_{primary} < \Lambda_{secondary} \]  
(eq. 44)

Due to this core non-homogeneity, the physical turns ratio \( (N) \) is not equal to the electrical turns \( (n) \) ratio that is given by the primary and secondary inductances (Equation 45).

\[ \frac{N_p}{N_s} = \sqrt{\frac{L_{primary}}{L_{secondary}}} \]  
(eq. 45)

Where:

\( N_p \) – is the primary winding turns number

\( N_s \) – is the secondary winding turns number

The number of the secondary winding turns can be calculated based on the magnetic conductivity for the secondary winding and the required secondary inductance (Equation 46).

\[ N_s = \sqrt{\frac{L_{secondary}}{A_{L_{secondary}}}} \]  
(eq. 46)

The air gap position also affects the total transformer leakage inductance, which needs to be adjusted to the required value.

The primary and secondary magnetic conductivities calculation and the total transformer stray flux calculation are not a simple task for a transformer with divided bobbin. Finite Element numerical Methods (FEM) with a precisely prepared model need to be used. Often the “cut-and-try” method is used during the transformer prototype design.

Finally, the secondary winding composed from two turns \( (N_s = 2) \) of copper strip has been used in this LLC transformer design to reach the required secondary inductance.

The auxiliary winding is used to power the SMPS primary controllers during normal and no load operating conditions. The auxiliary voltage of 18 V needs to be used for nominal operating conditions to assure a sufficient VCC level when the board is not loaded. The coupling coefficient between auxiliary and secondary windings has to be as high as possible to assure proper auxiliary voltage regulation. Thus it is beneficial to locate the auxiliary winding directly above the secondary windings. The safety requirements then push for triple insulated wire. The required number of turns for the auxiliary winding can be calculated using Equation 47.

\[ N_{aux} = \frac{V_{aux} + V_{f_{aux}}}{V_{out} + V_{f_{SR}}} \cdot N_s = \frac{18 + 0.7}{12 + 0.2} \cdot 2 = 3 \text{ turns} \]  
(eq. 47)

Where:

\( V_{aux} \) – is the target auxiliary voltage

\( V_{f_{aux}} \) – is the forward voltage drop of the diode used in the auxiliary VCC path

\( V_{f_{SR}} \) – is the forward voltage drop of the SR system including layout dropouts

The primary winding RMS current can be calculated using Equation 48.

\[ I_{primary\_RMS\_nom} = \sqrt{\frac{1}{8} \left( \frac{I_{out\_nom}^2 \cdot \pi^2 \cdot G_{nom}^2 + V_{bulk\_nom}^2}{24 \cdot L_{m}^2 \cdot f_{op\_nom}^2} \right)} \]  
(eq. 48)

\[ = \sqrt{\frac{1}{8} \left( 20^2 \cdot \pi^2 \cdot 0.0618^2 + \frac{395^2}{24 \cdot (715 \cdot 10^{-6})^2 \cdot (80 \cdot 10^3)^2} \right)} = 1.46 \text{ A} \]

The secondary winding RMS current for operation in resonant frequency and full load conditions is the same as the secondary rectifier current (Equation 49).

\[ I_{sec\_RMS} = I_{out\_nom} \cdot \frac{\pi}{4} = 20 \cdot \frac{\pi}{4} = 15.7 \text{ A} \]  
(eq. 49)

The LLC transformer skin effect needs to be considered during windings design for the nominal operating frequency. The skin depth for copper wire can be calculated based on Equation 50.

\[ \delta = \frac{65}{\sqrt{\frac{f_{op\_nom}}{80 \cdot 10^3}}} = \frac{65}{\sqrt{0.23}} = 0.23 \text{ mm} \]  
(eq. 50)
The maximum winding wire diameter that will be effectively used by the AC current is then two times higher than the calculated skin depth i.e. $\phi = 0.46$ mm. It makes no sense to use wires with higher diameter in primary or secondary windings because current cannot penetrate deeper into the conductor than to the calculated skin depth.

As aforementioned, the proximity effect caused by the primary and secondary windings positioning is another limitation in transformers with divided bobbin construction. The winding turns located closer to the opposite winding on the bobbin are affected by the field of other turns from the winding and have the strongest proximity effect. Proximity effect analysis is out of scope of this application note – one can refer to Reference 12 for more information on this subject.

After considering the skin effect and proximity effect it is evident that the best solution to winding construction is to use litz wire composed of several insulated conductors with diameter smaller than 0.46 mm. The secondary winding conducts a high RMS current compared to the primary, so it is beneficial to use copper strip lines instead of multiple litz wires. The primary winding has been implemented with litz wire 22xØ0.16. The secondary windings are composed of copper strip lines 8 mm wide and 0.2 mm thick. The auxiliary winding is composed of three turns of triple insulated wire with a diameter of $\phi = 0.25$ mm. This winding is located directly above the secondary windings to assure good coupling as mentioned above.

Some manufacturers specify the leakage inductance under the condition of all secondary windings shorted. This approach cannot be applied for a center tapped secondary side design because only one winding from the pair contributes resonance each switching period half cycle. Figure 20 with Table 2 shows how to measure the leakage inductances of a transformer with center tapped secondary side.

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Measured Between Pins</th>
<th>Secondary Pins Configuration</th>
</tr>
</thead>
<tbody>
<tr>
<td>$L_{lk(p-s1)}$</td>
<td>A–B</td>
<td>C–D short D–E open</td>
</tr>
<tr>
<td>$L_{lk(p-s2)}$</td>
<td>A–B</td>
<td>C–D open D–E short</td>
</tr>
<tr>
<td>$L_{lk(total)}$</td>
<td>A–B</td>
<td>C–D short D–E short</td>
</tr>
<tr>
<td>$L_{primary}$</td>
<td>A–B</td>
<td>C–D open D–E open</td>
</tr>
</tbody>
</table>

It is necessary to assure good matching between $L_{lk(p-s1)}$ and $L_{lk(p-s2)}$ leakage inductances otherwise the series resonant frequency would differ in each switching half cycle. As a result, the secondary current through each secondary branch would differ. The secondary current difference would increase losses and temperature in one of the secondary branches.

Figure 21 shows the simulated results for a case where the secondary currents leakage inductances imbalance is 5%.

Other possible sources of imbalance in the LLC power stage are the secondary layout parasitic inductances. The transformer turns ratio between primary and secondary is quite high for a 12 V output application. When reflected to the resonant tank circuitry, the secondary parasitic inductances are multiplied by the transformer turns ratio squared. This means that even very small secondary layout parasitic inductance asymmetry (like 50 nH) causes a big difference in resonant frequencies for each switching half period. The secondary layout thus needs to be as symmetrical as possible to achieve balanced LLC stage operation.
The final transformer specification is summarized in below figures and tables.

**Figure 22. The Transformer Windings Arrangement Within the Bobbin**

**Figure 23. Transformer Windings Pinout**

**Figure 24. Transformer Winding Directions**

**Table 3. TRANSFORMER PRIMARY INDUCTANCE SPECIFICATION**

<table>
<thead>
<tr>
<th>Primary Inductance</th>
<th>$L_p$ (μH)</th>
<th>Tolerance</th>
<th>$R$ (mΩ)</th>
<th>Tolerance</th>
</tr>
</thead>
<tbody>
<tr>
<td>Between Pins</td>
<td>3</td>
<td>5</td>
<td>715</td>
<td>±10%</td>
</tr>
</tbody>
</table>

**Table 4. TRANSFORMER LEAKAGE INDUCTANCES SPECIFICATION**

<table>
<thead>
<tr>
<th>Primary Inductance</th>
<th>$L_{LK}$ (μH)</th>
<th>Tolerance</th>
<th>Shorted Pins</th>
</tr>
</thead>
<tbody>
<tr>
<td>Between Pins</td>
<td>3</td>
<td>5</td>
<td>130.5</td>
</tr>
<tr>
<td>Between Pins</td>
<td>3</td>
<td>5</td>
<td>131.8</td>
</tr>
<tr>
<td>Between Pins</td>
<td>3</td>
<td>5</td>
<td>126.8</td>
</tr>
</tbody>
</table>
Table 5. TRANSFORMER WINDINGS SPECIFICATION

<table>
<thead>
<tr>
<th>Winding</th>
<th>Pin #</th>
<th>Turns and Gauge</th>
<th>Layers (Turns)</th>
<th>Winding Method</th>
<th>Insulation Tape</th>
</tr>
</thead>
<tbody>
<tr>
<td>W1</td>
<td>3, 5</td>
<td>38 UEW+NY LIT Z 0.16lx22# Grade 2 (NEMA MW80C/IEC 317–21) Thermal Class 155°C</td>
<td>5 (9 + 9 + 9 + 2)</td>
<td>CW Closed</td>
<td></td>
</tr>
<tr>
<td>W2</td>
<td>9, 10</td>
<td>12, 13 2 Cu Foil W = 8 mm T = 0.2 mm</td>
<td>2</td>
<td>CCW</td>
<td>2 mils 9 mm</td>
</tr>
<tr>
<td>W3</td>
<td>12, 13</td>
<td>15, 16 2 Cu Foil W = 8 mm T = 0.2 mm</td>
<td>2</td>
<td>CCW</td>
<td>2 mils 9 mm</td>
</tr>
<tr>
<td>W4</td>
<td>8, 7</td>
<td>3 TIW 0.250 Thermal Class B</td>
<td>1</td>
<td>CW Closed</td>
<td></td>
</tr>
</tbody>
</table>

PCB Design

The PCB layout of the LLC stage primary side is not very critical because switching of the main MOSFETs happens only under ZVS conditions and the influence of the PCB parasitic inductances on the operating frequency is negligible. The LLC stage secondary side layout is very critical especially in applications with low output voltages.

It is recommended that both paths from the secondary windings to the filtering capacitor bank should be made with the same length. A difference in parasitic inductance between paths results in a different resonant frequency for each half of the switching period. As the secondary RMS current is high, the parasitic resistance of the secondary layout should be minimized. This SMPS is designed on a two layer PCB with 70 µm copper plating.

Results

Please follow the steps detailed in the test procedure for the NCP4303 demo/evaluation board if testing the demoboard performance. Below measurements are shown for further information on how this design operates in practice.

Thanks

I would like to thank the below companies for providing the samples used in this demoboard.
Epcs – http://www.epcos.com
Pulse – http://www.pulseeng.com
Wurth – http://www.we-online.com
Coilcraft – http://www.coilcraft.com

Conclusion

This demoboard shows only one of many possible implementations of the NCP4303A/B synchronous rectification controller and is not intended as a final design for end customers. The main goal of this document is to introduce a typical application and illustrate how the various features help to decrease total cost and increase SMPS efficiency. Optional features are included in the PCB layout, thus it is easy to update the application according to specific requests.

References:

1. NCP4303 data sheet
2. NCP1605 data sheet
3. NCP1397 data sheet
4. Application note AND8257/D
5. Application note AND8327/D
6. Application note AND8281/D
7. Bo Yang – Topology Investigation for Front–End DC–DC Power Conversion for Distributed Power System
10. ON Semiconductor documentation TND399/D – 216 W All in One SMPS Reference Design
12. Xi Nan, C. R. Sullivan – An Improved Calculation of Proximity Effect Loss in High–Frequency Windings of Round Conductor
Figure 25. Application Input Current Measured for 110 VAC / 60 Hz Input and Full Load Conditions

Figure 26. Application Input Current Measured for 230 VAC / 50 Hz Input and Full Load Conditions

Figure 27. LLC Primary Current and Bridge Voltage for I_{load} = 20 A

Figure 28. LLC Primary Current and Bridge Voltage for I_{load} = 10 A

Figure 29. LLC Primary Current and Bridge Voltage for I_{load} = 5 A

Figure 30. LLC Primary Current and Bridge Voltage for I_{load} = 2.5 A
Figure 31. LLC Primary Current and Bridge Voltage for $I_{\text{load}} = 0$ A, SR is Operating

Figure 32. LLC Primary Current and Bridge Voltage for $I_{\text{load}} = 0$ A, SR is Not Operating

Figure 33. SMPS Response to Transient Loading 0 A to 20 A, 1.6 A/μs

Figure 34. SMPS Response to Transient Loading 20 A to 0 A, 1.6 A/μs

Figure 35. SMPS response to Transient Loading 2 A to 20 A, 1.6 A/μs

Figure 36. SMPS Response to Transient Loading 20 A to 2 A, 1.6 A/μs
Figure 37. SMPS Response to Transient Loading
8 A to 20 A, 1.6 A/μs

Figure 38. SMPS Response to Transient Loading
20 A to 8 A, 1.6 A/μs

Figure 39. Output Voltage Ripple Under Full Load Conditions

Figure 40. Bulk Voltage Ripple Image in the Output Voltage Under Full Load Conditions, 110 Vac/60 Hz

Figure 41. Output Voltage Ripple During No Load Conditions – SR is Turned Off

Figure 42. Transition From Full Load to Output Short–Circuit
Figure 43. Transition From No Load Operation to Output Short-Circuit

Figure 44. SMPS Operation Under Overload Conditions, Restart Time Given by $V_{CC}$ Restart

Figure 45. Secondary Side Currents and SR Gate Drive Signals for $I_{out} = 2.5$ A, IRFB3206

Figure 46. Secondary Side Currents, SR Gate and $V_{ds}$ signals for $I_{out} = 20$ A, IRFB3206

Figure 47. Secondary SR Gate Signals Comparison for Compensated and Uncompensated SR System $I_{out} = 20$ A, IRFB3206

Figure 48. Secondary Side Currents, SR Gate and $V_{ds}$ Signals for $I_{out} = 20$ A, IPP015N04N – Uncompensated
Figure 49. Secondary Side Currents, SR Gate and $V_{ds}$ Signals for $I_{out} = 20$ A, IPP015N04N – Compensated

Figure 50. Demo Board Efficiency versus Output Current for Compensated SR System and IRFB3206 SR MOSFETs
Figure 51. Demoboard Full Load Efficiency versus Input Voltage for Compensated SR System and IRFB3206 SR MOSFETs

Figure 52. Demoboard No Load Consumption for SR System Working and Turned Off
Figure 53. Demoboard Consumption for 100 mW and 500 mW Loads (SR System Working)

Figure 54. LLC Stage Efficiency versus Output Current for Compensated and Uncompensated SR Systems Featuring IRFB3206 MOSFETs and Nominal Bulk Voltage of 400 Vdc
Figure 55. LLC Stage Efficiency versus Output Current for Compensated and Uncompensated SR Systems Featuring IPP015N04N MOSFETs and Nominal Bulk Voltage of 400 Vdc

Figure 56. Conducted EMI Signature of the Board at Full Load and 110 VAC Input
Figure 57. Conducted EMI Signature of the Board at Full Load and 230 V_{AC} Input
Figure 58. Demoboard Schematic Including PCB Options
Figure 59. Top Side of the PCB

Figure 60. Bottom Side of the PCB
Figure 61. Top Labels

Figure 62. Bottom Labels
Figure 63. Demoboard Photo – Top Side

Figure 64. Demoboard Photo – Bottom Side
Figure 65. Demoboard Photo, Top Side with Measured Temperatures on the Full Loaded Board

Figure 66. Detail Photo of the SR Compensation Inductances
Table 6. BILL OF MATERIALS FOR THE NCP4303 DEMO BOARD

<table>
<thead>
<tr>
<th>Designator</th>
<th>Qty</th>
<th>Description</th>
<th>Value</th>
<th>Tolerance</th>
<th>Footprint</th>
<th>Manufacturer</th>
<th>Manufacturer Part Number</th>
<th>Substitution Allowed</th>
<th>Pb-Free</th>
</tr>
</thead>
<tbody>
<tr>
<td>B1</td>
<td>1</td>
<td>Bridge Rectifier</td>
<td>KBU8M</td>
<td>-</td>
<td>KBU8M</td>
<td>Fairchild</td>
<td>KBU8M</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>C1</td>
<td>1</td>
<td>Electrolytic Capacitor</td>
<td>22 mF / 25 V</td>
<td>20%</td>
<td>Through Hole</td>
<td>Koshin</td>
<td>KZH-025V220MC110</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>C3, C12, C42</td>
<td>3</td>
<td>Electrolytic capacitor</td>
<td>220 mF / 25 V</td>
<td>20%</td>
<td>Through Hole</td>
<td>Koshin</td>
<td>KZH-025V221MF115</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>C2, C13, C27</td>
<td>3</td>
<td>MKP Capacitor</td>
<td>NU</td>
<td>-</td>
<td>805</td>
<td>-</td>
<td>-</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>C8, C14, C20, C55</td>
<td>4</td>
<td>Ceramic Capacitor</td>
<td>1 mF</td>
<td>10%</td>
<td>Through Hole</td>
<td>Kemet</td>
<td>K1206F105K5RACTU</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>C15, C33, C47</td>
<td>3</td>
<td>MKP Capacitor</td>
<td>1.0 nF / 275 Vac</td>
<td>20%</td>
<td>Through Hole</td>
<td>Epcos</td>
<td>B3293C3105M</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>C16, C17</td>
<td>1</td>
<td>Electrolytic Bulk Capacitor</td>
<td>100 μF / 450 V</td>
<td>20%</td>
<td>Through Hole</td>
<td>Koshin</td>
<td>KPH-450V100UF</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>C50</td>
<td>1</td>
<td>Ceramic Capacitor</td>
<td>NU</td>
<td>-</td>
<td>805</td>
<td>-</td>
<td>-</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>C26</td>
<td>1</td>
<td>Ceramic Capacitor</td>
<td>1.2 nF</td>
<td>10%</td>
<td>805</td>
<td>Kemet</td>
<td>C0805C124K1RACTU</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>C38</td>
<td>1</td>
<td>Ceramic Capacitor</td>
<td>560 pF</td>
<td>10%</td>
<td>805</td>
<td>Kemet</td>
<td>C0805C61K5RACTU</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>C29</td>
<td>1</td>
<td>Ceramic Capacitor</td>
<td>68 nF</td>
<td>10%</td>
<td>805</td>
<td>Kemet</td>
<td>C0805C683K5RACTU</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>C29</td>
<td>1</td>
<td>Ceramic Capacitor</td>
<td>220 pF</td>
<td>10%</td>
<td>Through Hole</td>
<td>Kemet</td>
<td>C0805C221K5RACTU</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>C30, C31</td>
<td>2</td>
<td>Ceramic Capacitor</td>
<td>22 nF / 1 kV</td>
<td>10%</td>
<td>1812</td>
<td>Kemet</td>
<td>C1812C223KDRACTU</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>C32, C37</td>
<td>2</td>
<td>Ceramic Capacitor</td>
<td>NU</td>
<td>-</td>
<td>1206</td>
<td>-</td>
<td>-</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>C34</td>
<td>1</td>
<td>Ceramic Capacitor</td>
<td>6.8 nF</td>
<td>10%</td>
<td>805</td>
<td>Kemet</td>
<td>C0805C826K5RACTU</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>C35</td>
<td>1</td>
<td>Ceramic Capacitor</td>
<td>100 pF</td>
<td>10%</td>
<td>805</td>
<td>Kemet</td>
<td>C0805C101K5RACTU</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>C36, C39</td>
<td>2</td>
<td>Ceramic Capacitor</td>
<td>470 nF</td>
<td>10%</td>
<td>1206</td>
<td>Kemet</td>
<td>C1206C474K5RACTU</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>C4, C25</td>
<td>2</td>
<td>Ceramic Capacitor</td>
<td>3.9 nF</td>
<td>10%</td>
<td>1206</td>
<td>Kemet</td>
<td>C1206C392K5RACTU</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>C5, C9, C40, C41, C53, C54</td>
<td>6</td>
<td>Ceramic Capacitor</td>
<td>100 nF</td>
<td>10%</td>
<td>1206</td>
<td>Kemet</td>
<td>C1206C104K5RACTU</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>C43, C51</td>
<td>2</td>
<td>Ceramic Capacitor</td>
<td>10 nF</td>
<td>10%</td>
<td>805</td>
<td>Kemet</td>
<td>C0805C103K5RACTU</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>C44</td>
<td>1</td>
<td>Capacitor</td>
<td>NU</td>
<td>-</td>
<td>Through Hole</td>
<td>-</td>
<td>-</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>C49</td>
<td>1</td>
<td>Ceramic Capacitor</td>
<td>NU</td>
<td>-</td>
<td>1206</td>
<td>-</td>
<td>-</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>C46</td>
<td>1</td>
<td>Ceramic Capacitor</td>
<td>47 nF</td>
<td>10%</td>
<td>805</td>
<td>Kemet</td>
<td>C0805C473K5RACTU</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>C48</td>
<td>1</td>
<td>Ceramic Capacitor</td>
<td>NU</td>
<td>-</td>
<td>805</td>
<td>-</td>
<td>-</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>C49</td>
<td>1</td>
<td>Ceramic Capacitor</td>
<td>1 nF</td>
<td>10%</td>
<td>805</td>
<td>Kemet</td>
<td>C0805C102K5RACTU</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>C52, C57</td>
<td>2</td>
<td>Ceramic Capacitor</td>
<td>2.2 nF</td>
<td>10%</td>
<td>805</td>
<td>Kemet</td>
<td>C0805C222K5RACTU</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>C56</td>
<td>1</td>
<td>Electrolytic Capacitor</td>
<td>4.7 mF / 50 V</td>
<td>20%</td>
<td>Through Hole</td>
<td>Koshin</td>
<td>K1J-050V47MC110</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>C7, C18</td>
<td>2</td>
<td>Metal Film Capacitor</td>
<td>15 nF / 1600 V</td>
<td>5%</td>
<td>Through Hole</td>
<td>Epcos</td>
<td>B32652A1153J</td>
<td>No</td>
<td>Yes</td>
</tr>
<tr>
<td>C8, C9, C10, C11, C21, C22, C23, C24</td>
<td>8</td>
<td>Electrolytic Capacitor</td>
<td>1000 mF / 35 V</td>
<td>20%</td>
<td>Through Hole</td>
<td>Koshin</td>
<td>KZH-035V102MH250</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>CY1, CY2, CY3</td>
<td>3</td>
<td>Ceramic Capacitor</td>
<td>2.2 nF / Y1/X1</td>
<td>20%</td>
<td>Through Hole</td>
<td>Murata</td>
<td>DE1E3KX22MA5B</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>D1, D3, D7, D14, D15, D21, D22, D23, R6</td>
<td>9</td>
<td>Switching Diode</td>
<td>MMDS4148</td>
<td>-</td>
<td>SOD-123</td>
<td>ON Semiconductor</td>
<td>MMDS4148T3G</td>
<td>No</td>
<td>Yes</td>
</tr>
<tr>
<td>D10, D11</td>
<td>2</td>
<td>Surface Mount Ultrastat Power Rectifier</td>
<td>MURA160</td>
<td>-</td>
<td>SMA</td>
<td>ON Semiconductor</td>
<td>MURA160T3G</td>
<td>No</td>
<td>Yes</td>
</tr>
<tr>
<td>D12, D13</td>
<td>2</td>
<td>Diode</td>
<td>NU</td>
<td>-</td>
<td>SOD-123</td>
<td>-</td>
<td>-</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>D14, D17, D18, D19</td>
<td>4</td>
<td>Diode</td>
<td>NU</td>
<td>-</td>
<td>SOD-123</td>
<td>-</td>
<td>-</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>D2</td>
<td>1</td>
<td>Diode</td>
<td>NU</td>
<td>-</td>
<td>SOD-123</td>
<td>-</td>
<td>-</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>D4</td>
<td>1</td>
<td>Standard Recovery Rectifier</td>
<td>1N5408</td>
<td>-</td>
<td>Axial Lead</td>
<td>ON Semiconductor</td>
<td>1N5406RLG</td>
<td>No</td>
<td>Yes</td>
</tr>
<tr>
<td>D5</td>
<td>1</td>
<td>Soft Recovery Rectifier</td>
<td>M6RF860</td>
<td>-</td>
<td>TO220 (2 LEAD)</td>
<td>ON Semiconductor</td>
<td>M6RF860G</td>
<td>No</td>
<td>Yes</td>
</tr>
<tr>
<td>D6, D9</td>
<td>2</td>
<td>Diode</td>
<td>NU</td>
<td>-</td>
<td>SMA</td>
<td>-</td>
<td>-</td>
<td>Yes</td>
<td>Yes</td>
</tr>
</tbody>
</table>
### Table 6. BILL OF MATERIALS FOR THE NCP4303 DEMO BOARD

<table>
<thead>
<tr>
<th>Designator</th>
<th>Qty</th>
<th>Description</th>
<th>Value</th>
<th>Tolerance</th>
<th>Footprint</th>
<th>Manufacturer</th>
<th>Manufacturer Part Number</th>
<th>Substitution Allowed</th>
<th>Pb-Free</th>
</tr>
</thead>
<tbody>
<tr>
<td>D8</td>
<td>1</td>
<td>Zener Diode</td>
<td>7.5 V</td>
<td>5%</td>
<td>SOD-123</td>
<td>ON Semiconductor</td>
<td>MM52Z7VST1G</td>
<td>No</td>
<td>Yes</td>
</tr>
<tr>
<td>HEATSINK_1</td>
<td>1</td>
<td>Heat Sink</td>
<td>SK 454 150 SA</td>
<td>–</td>
<td>SK 454 150 SA</td>
<td>Fischer Elektronik</td>
<td>SK 454 150 SA</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>HEATSINK_2</td>
<td>1</td>
<td>Heat Sink</td>
<td>SK 454 135 SA</td>
<td>–</td>
<td>SK 454 135 SA</td>
<td>Fischer Elektronik</td>
<td>SK 454 135 SA</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>IC1, IC2</td>
<td>2</td>
<td>Secondary Side Synchronous Rectifier</td>
<td>NCP4303B</td>
<td>–</td>
<td>SOIC-8</td>
<td>ON Semiconductor</td>
<td>NCP4303BDR2G</td>
<td>No</td>
<td>Yes</td>
</tr>
<tr>
<td>IC3</td>
<td>1</td>
<td>Power Factor Controller</td>
<td>NCP1605</td>
<td>–</td>
<td>SOIC–16</td>
<td>ON Semiconductor</td>
<td>NCP1605ADR2G</td>
<td>No</td>
<td>Yes</td>
</tr>
<tr>
<td>IC4</td>
<td>1</td>
<td>Programmable Precision Reference</td>
<td>TL431</td>
<td>0.4%</td>
<td>TO–92</td>
<td>ON Semiconductor</td>
<td>TL431BCLPG</td>
<td>No</td>
<td>Yes</td>
</tr>
<tr>
<td>IC5</td>
<td>1</td>
<td>Resonant Mode Controller</td>
<td>NCP1397B</td>
<td>–</td>
<td>SOIC–16</td>
<td>ON Semiconductor</td>
<td>NCP1397BDR2G</td>
<td>No</td>
<td>Yes</td>
</tr>
<tr>
<td>J1</td>
<td>1</td>
<td>Input Terminal Block</td>
<td>Pitch 7.5 mm</td>
<td>–</td>
<td>CTB0110/2</td>
<td>Camden El.</td>
<td>CTB0110/2</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>JP2</td>
<td>1</td>
<td>Jumper 1x2</td>
<td>–</td>
<td>–</td>
<td>2 x 2.54 mm</td>
<td>Various</td>
<td>–</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>JP3</td>
<td>1</td>
<td>Jumper 1x3</td>
<td>–</td>
<td>–</td>
<td>3 x 2.54 mm</td>
<td>Various</td>
<td>–</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>L1, L8</td>
<td>2</td>
<td>Inductor – Wire Strap</td>
<td>–</td>
<td>–</td>
<td>Wire Strap</td>
<td>–</td>
<td>–</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>L12, L13</td>
<td>2</td>
<td>Inductor</td>
<td>100 μH</td>
<td>20%</td>
<td>DO5040H</td>
<td>Coilcraft</td>
<td>DO5040H–104MLB</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>L14</td>
<td>1</td>
<td>Inductor</td>
<td>NU</td>
<td>–</td>
<td>–</td>
<td>–</td>
<td>–</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>L15</td>
<td>1</td>
<td>EMI filter</td>
<td>7 mH</td>
<td>15%</td>
<td>TLBI</td>
<td>Pulse</td>
<td>6001.0069</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>L2</td>
<td>1</td>
<td>Inductor</td>
<td>200 nH</td>
<td>20%</td>
<td>L–US20A</td>
<td>Bohemia Electric</td>
<td>TC–05001510–00</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>L3</td>
<td>1</td>
<td>Inductor</td>
<td>NU</td>
<td>–</td>
<td>–</td>
<td>–</td>
<td>–</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>L4, L5, L6, L9, L10, L11</td>
<td>6</td>
<td>Inductor</td>
<td>NU</td>
<td>–</td>
<td>–</td>
<td>–</td>
<td>–</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>L7</td>
<td>1</td>
<td>Inductor</td>
<td>120 μH</td>
<td>10%</td>
<td>2722.0005C</td>
<td>Pulse</td>
<td>2722.0005C</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>OK1</td>
<td>1</td>
<td>Opto Coupler</td>
<td>HCPL–817</td>
<td>–</td>
<td>DIP–4</td>
<td>Avago Technologies</td>
<td>HCPL–817–000E</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>Q1</td>
<td>1</td>
<td>General Purpose Transistor</td>
<td>NU</td>
<td>–</td>
<td>SOT–123</td>
<td>–</td>
<td>–</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>Q10, Q11</td>
<td>2</td>
<td>General Purpose Transistor NPN</td>
<td>BC846</td>
<td>–</td>
<td>SOT–123</td>
<td>ON Semiconductor</td>
<td>BC846ALT1G</td>
<td>No</td>
<td>Yes</td>
</tr>
<tr>
<td>Q2, Q9</td>
<td>2</td>
<td>MOSFET transistor</td>
<td>IRFB3206</td>
<td>–</td>
<td>TO–220</td>
<td>International Rectifier</td>
<td>IRFS3206GPBF</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>Q3, Q5</td>
<td>2</td>
<td>MOSFET transistor</td>
<td>STP12NM60FP</td>
<td>–</td>
<td>TO–220</td>
<td>ST Microelectronics</td>
<td>STP12NM60FP</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>Q4</td>
<td>1</td>
<td>MOSFET transistor</td>
<td>STP20NM60FP</td>
<td>–</td>
<td>TO–220</td>
<td>ST Microelectronics</td>
<td>STP20NM60FP</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>Q6</td>
<td>1</td>
<td>High Voltage Transistor NPN</td>
<td>MPSA44</td>
<td>–</td>
<td>TO–92</td>
<td>ON Semiconductor</td>
<td>MPSA44RL1G</td>
<td>No</td>
<td>Yes</td>
</tr>
<tr>
<td>Q7</td>
<td>1</td>
<td>PNP General Purpose Transistor</td>
<td>BC807–16L</td>
<td>–</td>
<td>SOT–22</td>
<td>ON Semiconductor</td>
<td>BC807–16LT1G</td>
<td>No</td>
<td>Yes</td>
</tr>
<tr>
<td>Q8</td>
<td>1</td>
<td>Small Signal MOSFET N-Channel</td>
<td>2N7002E</td>
<td>–</td>
<td>SOT–23</td>
<td>ON Semiconductor</td>
<td>2N7002ET1G</td>
<td>No</td>
<td>Yes</td>
</tr>
<tr>
<td>R1, R10, R32</td>
<td>3</td>
<td>Resistor SMD</td>
<td>22 R</td>
<td>1%</td>
<td>805</td>
<td>Rohm Semiconductor</td>
<td>MCR10EZPF22R0</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>R100, R101</td>
<td>2</td>
<td>Resistor SMD</td>
<td>6.2 k</td>
<td>1%</td>
<td>805</td>
<td>Rohm Semiconductor</td>
<td>MCR10EZHF6201</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>R104</td>
<td>1</td>
<td>Resistor SMD</td>
<td>30 k</td>
<td>1%</td>
<td>805</td>
<td>Rohm Semiconductor</td>
<td>MCR10EZHF3002</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>R105</td>
<td>1</td>
<td>Resistor SMD</td>
<td>820 R</td>
<td>1%</td>
<td>805</td>
<td>Rohm Semiconductor</td>
<td>MCR10EZPF3002</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>R107</td>
<td>1</td>
<td>Resistor trough hole, high voltage</td>
<td>4.7 M</td>
<td>5%</td>
<td>414</td>
<td>Vishay</td>
<td>VR37000004704A100</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>R11, R39</td>
<td>2</td>
<td>Resistor SMD</td>
<td>11 k</td>
<td>1%</td>
<td>805</td>
<td>Rohm Semiconductor</td>
<td>MCR10EZPF1102</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>R12, R20, R33, R36, R51, R64, R73, R74</td>
<td>8</td>
<td>Resistor SMD</td>
<td>10 k</td>
<td>1%</td>
<td>805</td>
<td>Rohm Semiconductor</td>
<td>MCR10EZPF1002</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>R13, R49, R60, R84, R86, R90</td>
<td>6</td>
<td>Resistor SMD</td>
<td>1 k</td>
<td>1%</td>
<td>805</td>
<td>Rohm Semiconductor</td>
<td>MCR10EZPF1001</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>R14, R58, R59, R61, R62, R86, R96, R98</td>
<td>7</td>
<td>Resistor SMD</td>
<td>NU</td>
<td>–</td>
<td>805</td>
<td>–</td>
<td>–</td>
<td>Yes</td>
<td>Yes</td>
</tr>
</tbody>
</table>
Table 6. BILL OF MATERIALS FOR THE NCP4303 DEMO BOARD

<table>
<thead>
<tr>
<th>Designator</th>
<th>Qty</th>
<th>Description</th>
<th>Value</th>
<th>Tolerance</th>
<th>Footprint</th>
<th>Manufacturer</th>
<th>Manufacturer Part Number</th>
<th>Substitution Allowed</th>
<th>Pb-Free</th>
</tr>
</thead>
<tbody>
<tr>
<td>R15, R17, R18, R23, R27, R28, R31, R34, R35, R46, R47, R50</td>
<td>12</td>
<td>Resistor SMD</td>
<td>1.8 M</td>
<td>1%</td>
<td>805</td>
<td>Rohm Semiconductor</td>
<td>MCR10EZHF1804</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>R16, R22</td>
<td>2</td>
<td>Resistor SMD</td>
<td>47 k</td>
<td>5%</td>
<td>2010</td>
<td>Vishay</td>
<td>CRCW201047K0JNEF</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>R19, R66</td>
<td>2</td>
<td>Resistor SMD</td>
<td>56 k</td>
<td>1%</td>
<td>805</td>
<td>Rohm Semiconductor</td>
<td>MCR10EZHF5602</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>R2, R3, R24, R30, R78</td>
<td>5</td>
<td>Resistor SMD</td>
<td>0 R</td>
<td>-</td>
<td>805</td>
<td>Rohm Semiconductor</td>
<td>MCR10EZP000</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>R21</td>
<td>1</td>
<td>Resistor SMD</td>
<td>220 k</td>
<td>1%</td>
<td>805</td>
<td>Rohm Semiconductor</td>
<td>MCR10EZP2203</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>R25</td>
<td>1</td>
<td>Resistor SMD</td>
<td>47 R</td>
<td>1%</td>
<td>805</td>
<td>Rohm Semiconductor</td>
<td>MCR10EZP47R0</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>R29</td>
<td>1</td>
<td>Resistor SMD</td>
<td>1 k</td>
<td>1%</td>
<td>1206</td>
<td>Rohm Semiconductor</td>
<td>MCR10EZPF1001</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>R38</td>
<td>1</td>
<td>Resistor Through Hole</td>
<td>0.1 R / 3 W</td>
<td>1%</td>
<td>Axial Lead</td>
<td>Vishay</td>
<td>PAC300001007FAC000</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>R4, R68, R108</td>
<td>3</td>
<td>Resistor SMD</td>
<td>NU</td>
<td>-</td>
<td>805</td>
<td>-</td>
<td>-</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>R42, R52</td>
<td>2</td>
<td>Resistor SMD</td>
<td>24 k</td>
<td>1%</td>
<td>1206</td>
<td>Rohm Semiconductor</td>
<td>MCR10EZPF2402</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>R43, R53</td>
<td>2</td>
<td>Resistor SMD</td>
<td>220 R</td>
<td>5%</td>
<td>2010</td>
<td>Vishay</td>
<td>CRCW201020RJNEF</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>R44, R98</td>
<td>2</td>
<td>Resistor SMD</td>
<td>8.2 k</td>
<td>1%</td>
<td>805</td>
<td>Rohm Semiconductor</td>
<td>MCR10EZHF8201</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>R45, R55</td>
<td>2</td>
<td>Resistor SMD</td>
<td>10 R</td>
<td>1%</td>
<td>805</td>
<td>Rohm Semiconductor</td>
<td>MCR10EZPF1002</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>R46</td>
<td>1</td>
<td>Resistor SMD</td>
<td>430 k</td>
<td>1%</td>
<td>805</td>
<td>Rohm Semiconductor</td>
<td>MCR10EZPF4303</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>R54, R55</td>
<td>2</td>
<td>Resistor SMD</td>
<td>10 R</td>
<td>1%</td>
<td>805</td>
<td>Rohm Semiconductor</td>
<td>MCR10EZPF1003</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>R63, R103</td>
<td>2</td>
<td>Resistor SMD</td>
<td>2.2 R</td>
<td>1%</td>
<td>805</td>
<td>Rohm Semiconductor</td>
<td>MCR10EZP2203</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>R67</td>
<td>1</td>
<td>Resistor SMD</td>
<td>51 k</td>
<td>1%</td>
<td>805</td>
<td>Rohm Semiconductor</td>
<td>MCR10EZHF5102</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>R65</td>
<td>1</td>
<td>Resistor SMD</td>
<td>22 k</td>
<td>1%</td>
<td>805</td>
<td>Rohm Semiconductor</td>
<td>MCR10EZHF2202</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>R67, R106</td>
<td>2</td>
<td>Resistor SMD</td>
<td>13 k</td>
<td>1%</td>
<td>805</td>
<td>Rohm Semiconductor</td>
<td>MCR10EZHF1302</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>R69</td>
<td>1</td>
<td>Resistor SMD</td>
<td>100k</td>
<td>1%</td>
<td>805</td>
<td>Rohm Semiconductor</td>
<td>MCR10EZPF1003</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>R7, R37</td>
<td>2</td>
<td>Resistor SMD</td>
<td>39 k</td>
<td>1%</td>
<td>805</td>
<td>Rohm Semiconductor</td>
<td>MCR10EZHF3902</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>R70</td>
<td>1</td>
<td>Resistor SMD</td>
<td>24 k</td>
<td>1%</td>
<td>805</td>
<td>Rohm Semiconductor</td>
<td>MCR10EZHF2402</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>R71</td>
<td>1</td>
<td>Resistor SMD</td>
<td>62 k</td>
<td>1%</td>
<td>805</td>
<td>Rohm Semiconductor</td>
<td>MCR10EZHF6202</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>R72</td>
<td>1</td>
<td>Resistor SMD</td>
<td>220 R</td>
<td>1%</td>
<td>805</td>
<td>Rohm Semiconductor</td>
<td>MCR10EZHF2201</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>R75, R87</td>
<td>2</td>
<td>Resistor SMD</td>
<td>43 k</td>
<td>1%</td>
<td>805</td>
<td>Rohm Semiconductor</td>
<td>MCR10EZHF4302</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>R76</td>
<td>1</td>
<td>Resistor SMD</td>
<td>560 k</td>
<td>1%</td>
<td>805</td>
<td>Rohm Semiconductor</td>
<td>MCR10EZPF5603</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>R77, R82, R87</td>
<td>3</td>
<td>Resistor SMD</td>
<td>5.6 k</td>
<td>1%</td>
<td>805</td>
<td>Rohm Semiconductor</td>
<td>MCR10EZHF5601</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>R79</td>
<td>1</td>
<td>Resistor SMD</td>
<td>2.7 k</td>
<td>1%</td>
<td>805</td>
<td>Rohm Semiconductor</td>
<td>MCR10EZHF2701</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>R8, R9, R40, R41</td>
<td>4</td>
<td>Resistor SMD</td>
<td>27 R</td>
<td>1%</td>
<td>805</td>
<td>Rohm Semiconductor</td>
<td>MCR10EZPF27R0</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>R80, R102</td>
<td>2</td>
<td>Resistor SMD</td>
<td>27 k</td>
<td>1%</td>
<td>805</td>
<td>Rohm Semiconductor</td>
<td>MCR10EZHF2702</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>R81</td>
<td>1</td>
<td>Resistor SMD</td>
<td>47 k</td>
<td>1%</td>
<td>805</td>
<td>Rohm Semiconductor</td>
<td>MCR10EZHF4702</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>R83</td>
<td>1</td>
<td>Resistor SMD</td>
<td>15 k</td>
<td>1%</td>
<td>805</td>
<td>Rohm Semiconductor</td>
<td>MCR10EZHF1502</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>R89</td>
<td>1</td>
<td>Resistor SMD</td>
<td>12 k</td>
<td>1%</td>
<td>805</td>
<td>Rohm Semiconductor</td>
<td>MCR10EZHF1202</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>R91</td>
<td>1</td>
<td>NTC Thermistor</td>
<td>B57235S509M</td>
<td>20%</td>
<td>Disc – Radial</td>
<td>Epcos</td>
<td>B57235S509M</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>R92</td>
<td>1</td>
<td>Resistor SMD</td>
<td>7.5 k</td>
<td>1%</td>
<td>805</td>
<td>Rohm Semiconductor</td>
<td>MCR10EZHF2701</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>R93</td>
<td>1</td>
<td>Resistor SMD</td>
<td>200 k</td>
<td>1%</td>
<td>805</td>
<td>Rohm Semiconductor</td>
<td>MCR10EZPF2003</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>R94</td>
<td>1</td>
<td>Resistor SMD</td>
<td>2.2 k</td>
<td>1%</td>
<td>805</td>
<td>Rohm Semiconductor</td>
<td>MCR10EZHF2201</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>R95</td>
<td>1</td>
<td>Resistor SMD</td>
<td>9.1 k</td>
<td>1%</td>
<td>805</td>
<td>Rohm Semiconductor</td>
<td>MCR10EZHF9101</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>R96</td>
<td>1</td>
<td>Resistor SMD</td>
<td>18 R</td>
<td>1%</td>
<td>805</td>
<td>Rohm Semiconductor</td>
<td>MCR10EZPF18R0</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>R99</td>
<td>1</td>
<td>Resistor SMD</td>
<td>5.1 k</td>
<td>1%</td>
<td>805</td>
<td>Rohm Semiconductor</td>
<td>MCR10EZHF5101</td>
<td>Yes</td>
<td>Yes</td>
</tr>
</tbody>
</table>
## Table 6. BILL OF MATERIALS FOR THE NCP4303 DEMO BOARD

<table>
<thead>
<tr>
<th>Designator</th>
<th>Qty</th>
<th>Description</th>
<th>Value</th>
<th>Tolerance</th>
<th>Footprint</th>
<th>Manufacturer</th>
<th>Manufacturer Part Number</th>
<th>Substitution Allowed</th>
<th>Pb-Free</th>
</tr>
</thead>
<tbody>
<tr>
<td>SJ1</td>
<td>1</td>
<td>SMD Jumper</td>
<td>0 R</td>
<td>5%</td>
<td>805</td>
<td>Rohm Semiconductor</td>
<td>MCR10EZPJ000</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>SJ2</td>
<td>1</td>
<td>SMD Jumper</td>
<td>NU</td>
<td>–</td>
<td>–</td>
<td>–</td>
<td>–</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>TR1</td>
<td>1</td>
<td>Transformer</td>
<td>–</td>
<td>–</td>
<td>–</td>
<td>Pulse</td>
<td>See AN for spec</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>X1</td>
<td>2</td>
<td>Output Terminal Block</td>
<td>Pitch 5 mm</td>
<td>–</td>
<td>20.700M/2</td>
<td>IMO</td>
<td>20.700M/2</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>F1 – Cover</td>
<td>1</td>
<td>Cover, PCB Fuse Holder</td>
<td>–</td>
<td>–</td>
<td>–</td>
<td>Multicomponent</td>
<td>MCHTC-150M</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>F1 – Fuse</td>
<td>1</td>
<td>Fuse, Medium Delay</td>
<td>4 A</td>
<td>–</td>
<td>–</td>
<td>Bussmann</td>
<td>TDC 210-4A</td>
<td>Yes</td>
<td>Yes</td>
</tr>
<tr>
<td>F1 – Holder</td>
<td>1</td>
<td>Fuse Holder</td>
<td>–</td>
<td>–</td>
<td>–</td>
<td>Multicomponent</td>
<td>MCHTC-15M</td>
<td>Yes</td>
<td>Yes</td>
</tr>
</tbody>
</table>

80 PLUS is a registered trademark of ECOS Consulting.